

Four Output Differential Buffer for PCle Gen 2 with Spread

ICS9DS400

General Description

The 9DS400 is pin compatible to the 9DB403, but adds the ability to inject spread spectrum onto the incoming differential clock, while maintaining good phase noise.

Recommended Application

DB400 where spread spectrum needs to be added to the incoming clock.

Key Specifications

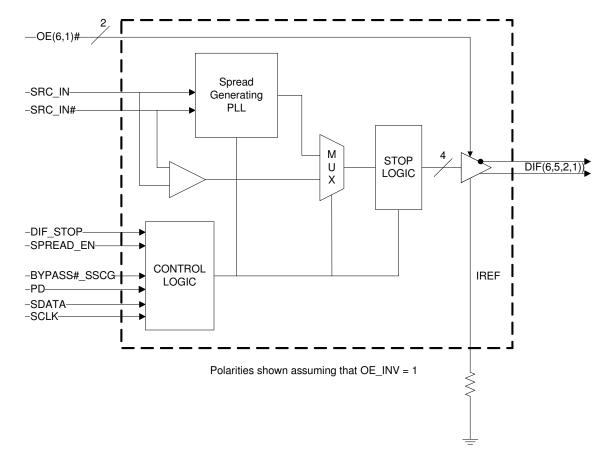
- Output cycle-cycle jitter < 50ps
- Output to Output skew <50ps
- Phase jitter: PCIe Gen1 < 86ps peak to peak
- Phase jitter: PCIe Gen2 < 3.0/3.1ps rms

Features/Benefits

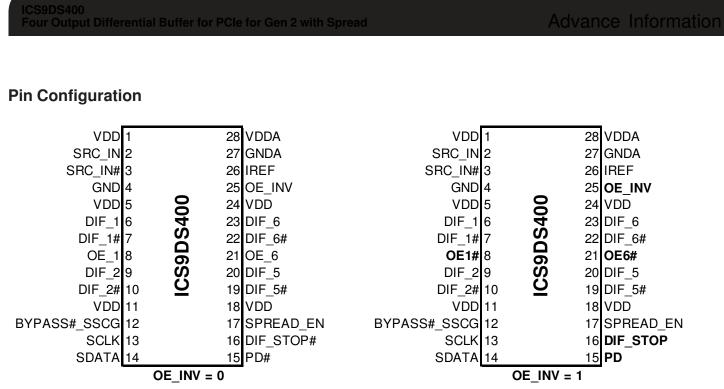
- Bypass mode
- Supports undriven differential outputs in PD# and SRC_STOP# modes for power management.

Output Features

- 4 0.7V current-mode differential output pairs.
- Supports Spread Injection mode and fanout mode.
- Two pin selectable down spread amounts: 0.5% and 0.25%.
- 50-110 MHz operation in PLL mode
- 50-400 MHz operation in Bypass mode



Functional Block Diagram



See Pin Description Table for pins w/internal pull up or pull down

See Pin Description Table for pins w/internal pull up or pull down

Power Groups

Pin N	umber	Description
VDD	GND	Description
1	4	SRC_IN/SRC_IN#
5,11,18, 24	4	DIF(1,2,5,6)
N/A	27	IREF
00	07	Analog VDD &
28	27	GND for PLL core

Pin Description for OE_INV = 0

PIN #	PIN NAME	PIN TYPE	DESCRIPTION	INTERNAL PULL UP OR PULL DOWN?
1	VDD	PWR	Power supply, nominal 3.3V	N/A
2	SRC_IN	IN	0.7 V Differential SRC TRUE input	N/A
3	SRC_IN#	IN	0.7 V Differential SRC COMPLEMENTARY input	N/A
4	GND	PWR	Ground pin.	N/A
5	VDD	PWR	Power supply, nominal 3.3V	N/A
6	DIF_1	OUT	0.7V differential true clock output	N/A
7	DIF_1#	OUT	0.7V differential Complementary clock output	N/A
8	OE_1	IN	Active high input for enabling output 1. 0 = tri-state outputs, 1= enable outputs	PULL UP
9	DIF_2	OUT	0.7V differential true clock output	N/A
10	DIF_2#	OUT	0.7V differential Complementary clock output	N/A
11	VDD	PWR	Power supply, nominal 3.3V	N/A
12	BYPASS#_SSCG	IN	Input to select Bypass(fan-out) or SSCG (PLL) mode 0 = Bypass mode, 1= SSCG mode	PULL UP
13	SCLK	IN	Clock pin of SMBus circuitry, 5V tolerant.	N/A
14	SDATA	I/O	Data pin for SMBus circuitry, 3.3V tolerant.	N/A
15	PD#	IN	Asynchronous active low input pin used to power down the device. The internal clocks are disabled and the VCO and the crystal osc. (if any) are stopped.	PULL UP
16	DIF STOP#	IN	Active low input to stop differential output clocks.	PULL UP
17	SPREAD EN	IN	Asynchronous, active high input to enable spread spectrum functionality.	PULL UP
18	VDD	PWR	Power supply, nominal 3.3V	N/A
19	DIF 5#	OUT	0.7V differential Complementary clock output	N/A
20	DIF_5	OUT	0.7V differential true clock output	N/A
21	OE_6	IN	Active high input for enabling output 6. 0 = tri-state outputs, 1= enable outputs	PULL UP
22	DIF 6#	OUT	0.7V differential Complementary clock output	N/A
23	DIF 6	OUT	0.7V differential true clock output	N/A
24	VDD	PWR	Power supply, nominal 3.3V	N/A
25	OE_INV	IN	This latched input selects the polarity of the OE pins. 0 = OE pins active high, 1 = OE pins active low (OE#)	N/A
26	IREF	OUT	This pin establishes the reference current for the differential current-mode output pairs. This pin requires a fixed precision resistor tied to ground in order to establish the appropriate current. 475 ohms is the standard value.	N/A
27	GNDA	PWR	Ground pin for the PLL core.	N/A
28	VDDA	PWR	3.3V power for the PLL core.	N/A

Pin Description for OE_INV = 1

PIN #	PIN NAME	PIN TYPE	DESCRIPTION	INTERNAL PULL UP OR PULL DOWN?
1	VDD	PWR	Power supply, nominal 3.3V	N/A
2	SRC_IN	IN	0.7 V Differential SRC TRUE input	N/A
3	SRC_IN#	IN	0.7 V Differential SRC COMPLEMENTARY input	N/A
4	GND	PWR	Ground pin.	N/A
5	VDD	PWR	Power supply, nominal 3.3V	N/A
6	DIF_1	OUT	0.7V differential true clock output	N/A
7	DIF_1#	OUT	0.7V differential Complementary clock output	N/A
8	OE1#	IN	Active low input for enabling DIF pair 1. 1 = tri-state outputs, 0 = enable outputs	PULL UP
9	DIF_2	OUT	0.7V differential true clock output	N/A
10	DIF_2#	OUT	0.7V differential Complementary clock output	N/A
11	VDD	PWR	Power supply, nominal 3.3V	N/A
12	BYPASS#_SS CG	IN	Input to select Bypass(fan-out) or SSCG (PLL) mode 0 = Bypass mode, 1= SSCG mode	PULL UP
13	SCLK	IN	Clock pin of SMBus circuitry, 5V tolerant.	N/A
14	SDATA	I/O	Data pin for SMBus circuitry, 3.3V tolerant.	N/A
15	PD	IN	Asynchronous active high input pin used to power down the device. The internal clocks are disabled and the VCO is stopped.	PULL UP
16	DIF STOP	IN	Active High input to stop differential output clocks.	PULL UP
17	SPREAD_EN	IN	Asynchronous, active high input to enable spread spectrum functionality.	PULL UP
18	VDD	PWR	Power supply, nominal 3.3V	N/A
19	DIF_5#	OUT	0.7V differential Complementary clock output	N/A
20	DIF_5	OUT	0.7V differential true clock output	N/A
21	OE6#	IN	Active low input for enabling DIF pair 6. 1 = tri-state outputs, 0 = enable outputs	PULL UP
22	DIF_6#	OUT	0.7V differential Complementary clock output	N/A
23	DIF_6	OUT	0.7V differential true clock output	N/A
24	VDD	PWR	Power supply, nominal 3.3V	N/A
25	OE_INV	IN	This latched input selects the polarity of the OE pins. 0 = OE pins active high, 1 = OE pins active low (OE#)	N/A
26	IREF	OUT	This pin establishes the reference current for the differential current-mode output pairs. This pin requires a fixed precision resistor tied to ground in order to establish the appropriate current. 475 ohms is the standard value.	N/A
27	GNDA	PWR	Ground pin for the PLL core.	N/A
28	VDDA	PWR	3.3V power for the PLL core.	N/A

ICS9DS400 Four Output Differential Buffer for PCIe for Gen 2 with Spread

Absolute Max

Symbol	Parameter	Min	Max	Units
VDD	3.3V Supply Voltage		4.6	V
V _{IL}	Input Low Voltage	GND-0.5		V
V _{IH}	Input High Voltage		V_{DD} +0.5V	V
Ts	Storage Temperature	-65	150	°C
Tcase	Case Temperature		115	°C
	Input ESD protection			
ESD prot	human body model	2000		V

Electrical Characteristics - Input/Supply/Common Output Parameters

 T_A =Over the Specified Operating Range; V_{DD} = 3.3 V +/-5%

T _A =Over the Specified O	perating Rar	nge; V _{DD} = 3.3 V +/-5%				$\langle \cdot \rangle$	
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input High Voltage	V _{IH}	3.3 V +/-5%	2	<	V _{DD} + 0.3	V	1
Input Low Voltage	V _{IL}	3.3 V +/-5%	GND - 0.3		0.8	V	1
Input High Current	I _{IH}	$V_{IN} = V_{DD}$	-5	$\overline{)}$	5	uA	1
Input Low Current	I _{IL1}	$V_{IN} = 0$ V; Inputs with no pull-up resistors	-5			uA	1
	I _{IL2}	V _{IN} = 0 V; Inputs with pull-up resistors	-200			uA	1
Operating Supply Current	I _{DD3.3OP}	Full Active, C _L = Full load;	7	\rightarrow	125	mA	1
Powerdown Current	I _{DD3.3PD}	all diff pairs driven	\bigcirc		30	mA	1
T Owerdown Ourrent	1003.3PD	all differential pairs tri-stated			6	mA	1
Input Frequency	Field	PCIe Mode (Bypass#/PLL= 1)	90	100.00	110	MHz	1
input i requeitcy	F _{iBYPASS}	Bypass Mode ((Bypass#/PLL= 0)	33	\land	400 🤇	MHz	1
Pin Inductance	L _{pin}			~	7	[⊘] nH	1
	CIN	Logic Inputs, except SRC_IN	1.5	$\langle \langle \rangle$	5	рF	1
Capacitance	CINSRC IN	SRC_IN differential clock inputs	1.5		2,7	pF	1,4
	Cout	Output pin capacitance			6	pF	1
Clk Stabilization	T _{STAB}	From V _{DD} Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock		S. S. S. C.	1	ms	1,2
SS Modulation Frequency	f _{MOD}	Assuming 100 MHz input (Triangular Modulation)	30	32.000	33	kHz	1
OE# Latency	t _{LATOE#}	DIF start after OE# assertion DIF stop after OE# deassertion			3	cycles	1,3
Tdrive_PD#	t _{DRVPD}	DIF output enable after PD# de-assertion			300	us	1,3
Tfall	t _E	Fall time of PD# and SRC_STOP#			5	ns	1
Trise	t _R)	Rise time of PD# and SRC_STOP#			5	ns	2
SMBus Voltage	VMAX	Maximum input voltage			5.5	V	1
Low-level Output Voltage	V _{OL}	@ I _{PULLUP}			0.4	V	1
Current sinking at VOL	I _{PULLUP}		4			mA	1
SCLK/SDATA Clock/Data Rise Time	t _{RSMB}	(Max VIL - 0.15) to (Min VIH + 0.15)			1000	ns	1
SCLK/SDATA Clock/Data Fall Time	t _{FSMB}	(Min VIH + 0.15) to (Max VIL - 0.15)			300	ns	1
SMBus Operating Frequency	f _{MAXSMB}	Maximum SMBus operating frequency			100	kHz	1,5

¹Guaranteed by design and characterization, not 100% tested in production.

²See timing diagrams for timing requirements.

³Time from deassertion until outputs are >200 mV

⁴SRC_IN input

⁵The differential input clock must be running for the SMBus to be active IDT™/ICS™ Four Output Differential Buffer for PCIe Gen 2 with Spread

Electrical Characteristics - Differential Clock Input Parameters TA = Over the Specified Operating Bange: $VDD = 3.3 \text{ V} \pm \frac{1}{5\%}$

TA =Over the Specified Operating Range; VDD = 3.3 V +/-5%								
SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES		
VIHDIF	Differential inputs (single-ended measurement)	600	800	1150	mV	1		
VILDIF	Differential inputs (single-ended measurement)	V _{SS} - 300	0	300	mV	1		
V _{COM}	Common Mode Input Voltage	300		1000	mV	1		
V _{SWING}	Peak to Peak value	300		1450	mV	1		
dv/dt	Measured differentially	0.4	\square	8	V/ns	1,2		
I _{IN}	$V_{IN} = V_{DD}, V_{IN} = GND$	-5	$\backslash \frown$	5	uA	1		
d _{tin}	Measurement from differential wavefrom	45		55	%	1		
J _{DIFIn}	Differential Measurement	0		125	ps	1		
	SYMBOL VIHDIF VILDIF VCOM VSWING dv/dt IIN dtin	SYMBOL CONDITIONS VIHDIF Differential inputs (single-ended measurement) VILDIF Differential inputs (single-ended measurement) V _{COM} Common Mode Input Voltage V _{SWING} Peak to Peak value dv/dt Measured differentially I _{IN} V _{IN} = V _{DD} , V _{IN} = GND dtin Measurement from differential wavefrom	SYMBOLCONDITIONSMIN V_{IHDIF} Differential inputs (single-ended measurement)600 V_{ILDIF} Differential inputs (single-ended measurement) $V_{SS} - 300$ V_{COM} Common Mode Input Voltage300 V_{SWING} Peak to Peak value300 dv/dt Measured differentially0.4 I_{IN} $V_{IN} = V_{DD}, V_{IN} = GND$ -5 d_{tin} Measurement from differential wavefrom45	SYMBOLCONDITIONSMINTYP V_{IHDIF} Differential inputs (single-ended measurement)600800 V_{ILDIF} Differential inputs (single-ended measurement) $V_{SS} - 300$ 0 V_{COM} Common Mode Input Voltage300 V_{SWING} Peak to Peak value300 dv/dt Measured differentially0.4 I_{IN} $V_{IN} = V_{DD}, V_{IN} = GND$ -5 d_{tin} Measurement from differential wavefrom45	SYMBOLCONDITIONSMINTYPMAX V_{IHDIF} Differential inputs (single-ended measurement)6008001150 V_{ILDIF} Differential inputs (single-ended measurement) $V_{SS} - 300$ 0300 V_{COM} Common Mode Input Voltage3001000 V_{SWING} Peak to Peak value3001450 dv/dt Measured differentially0.48 I_{IN} $V_{IN} = V_{DD}, V_{IN} = GND$ -55 d_{tin} Measurement from differential wavefrom4555	SYMBOLCONDITIONSMINTYPMAXUNITS V_{IHDIF} Differential inputs (single-ended measurement)6008001150mV V_{ILDIF} Differential inputs (single-ended measurement) $V_{SS} - 300$ 0300mV V_{COM} Common Mode Input Voltage3001000mV V_{SWING} Peak to Peak value3001450mV dv/dt Measured differentially0.48V/ns I_{IN} $V_{IN} = V_{DD}, V_{IN} = GND$ -55uA d_{tin} Measurement from differential wavefrom4555%		

¹ Guaranteed by design and characterization, not 100% tested in production. ²Slew rate measured through Vswing min centered around differential zero



Electrical Characteristics - DIF 0.7V Current Mode Differential Pair

TA =Over the Specified Operating Range; VDD = 3.3 V +/-5%; $C_L = 2pF$, $R_S = 33\Omega$, $R_P = 49.9\Omega$, $R_{REF} = 475\Omega$
--

PARAMETER	SYMBOL	$\frac{\text{nge, VDD} = 3.3 \text{ V } + -3\%; \text{ C}_{L} = 2\text{pr, } \text{R}_{S} = 3322}{\text{CONDITIONS}}$	MIN	TYP	MAX	UNITS	NOTES
Current Source Output Impedance	Zo ¹		3000			Ω	1
Voltage High	VHigh	Statistical measurement on single ended	660		850	mV	1,2
Voltage Low	VLow	signal using oscilloscope math function.	-150		150	\geq	1,2
Max Voltage	Vovs	Measurement on single ended signal			1150	mV	1
Min Voltage	Vuds	using absolute value.	-300	\geq	$(\land \land$	mv	1
Crossing Voltage (abs)	Vcross(ab s)		250		550	mV	1
Crossing Voltage (var)	d-Vcross	Variation of crossing over all edges	\bigcirc		140	mV	1
Rise Time	tr	V _{OL} = 0.175V, V _{OH} = 0.525V	175	\sim	700	ps	1
Fall Time	t _f	$V_{OH} = 0.525 V V_{OL} = 0.175 V$	175		700	ps	1
Rise Time Variation	d-t _r		\rightarrow	$\langle \rangle$	125	ps	1
Fall Time Variation	d-t _f		\sim	\searrow	125	ps	1
Duty Cycle	d _{t3}	Measurement from differential wavefrom	45		55	%	1
	t _{pdBYP}	Bypass Mode, V _T = 50%	2500		4500	ps	1
Skew, Input to Output	t _{pdPLL}	PLL Mode $V_T = 50\%$, Spread Off	-250		250	ps	1
Skew, Output to Output	t _{sk3}	V _T = 50%	~		50 🔨	ps	1
Jitter, Cycle to cycle	\sim	RLL mode		>	50	ps	1,3
JILLEI, CYCLE LO CYCLE	t _{jcyc-cyc}	Additive Jitter in Bypass Mode		\square	<u>(50)</u>	ps	1,3
		PCle Gen1 phase jitter (Additive in Bypass Mode)			10	ps (pk2pk)	1,4,5
	t _{jphase} BYP	PCIe Gen 2 Low Band phase jitter (Additive in Bypass Mode)			~ 0.1	ps (rms)	1,4,5
Jitter, Phase		PCIe Gen 2 High Band phase jitter (Additive in Bypass Mode)			0.5	ps (rms)	1,4,5
	D	PCle Gen 1 phase jitter			86	ps (pk2pk)	1,4,5
	t _{jphasePLL}	PCIe Gen 2 Low Band phase jitter			3	ps (rms)	1,4,5
		PCIe Gen 2 High Band phase jitter	~		3.1	ps (rms)	1,4,5

¹Guaranteed by design and characterization, not 100% tested in production.

 2 I_{REF} = V_{DD}/(3xR_R). For R_R = 475 Ω (1%), I_{REF} = 2.32mA. I_{OH} = 6 x I_{REF} and V_{OH} = 0.7V @ Z_O=50 Ω . 3 Measured from differential waveform

⁴ See http://www.pcisig.com for complete specs

⁵ Device driven by 932S421C or equivalent.

	urement ndow	1 Clock	1us	0.1s	0.1s	0.1s	1us	1 Clock		
Sy	mbol	Lg-	-SSC	-ppm error	0ppm	+ ppm error	+SSC	Lg+		
		Absolute Period	Short-term Average	Long-Term Average	Period	Long-Term Average	Short-term Average	Period		
Def	inition	Minimum Absolute Period	Minimum Absolute Period	Minimum Absolute Period	Nominal	Maximum	Maximum	Maximum	Units	Notes
	DIF 100	9.87400	9.99900	9.99900	10.00000	10.00100	10.05130	10.17630	ns	1,2,3
эг	DIF 133	7.41425	7.49925	7.49925	7.50000	7.50075	7.53845	7.62345	ns	1,2,4
Name	DIF 166	5.91440	5.99940	5.99940	6.00000	6.00060	6.03076	6.11576	ns	1,2,4
al N	DIF 200	4.91450	4.99950	4.99950	5.00000	5.00050	5.02563	5.11063	ns	1,2,4
Signal I	DIF 266	3.66463	3.74963	3.74963	3.75000	3.75038	3.76922	3.85422	ns	1,2,4
S	DIF 333	2.91470	2.99970	2.99970	3.00000	3.00030	3.01538	3.10038	ns	1,2,4
	DIF 400	2.41475	2.49975	2.49975	2.50000	2.50025	2.51282	2.59782	ns	1,2,4

Clock Periods Differential Outputs with Spread Spectrum Enabled

Clock Periods Differential Outputs with Spread Spectrum Disabled

	urement indow	1 Clock	1us	0.1s	0.1s	0.1s	1us	1 Clock		
Sy	mbol	Lg-	-SSC	-ppm error	0ppm	+ ppm error	+SSC	Lg+		
		Absolute Period	Short-term Average	Long-Term Average	Period	Long-Term Average	Short-term Average	Period		
Def	finition	Minimum Absolute Period	Minimum Absolute Period	Minimum Absolute Period	Nominal	Maximum	Maximum	Maximum	Units	Notes
	DIF 100	9.87400		9.99900	10.00000	10.00100		10.17630	ns	1,2,3
e	DIF 133	7.41425		7.49925	7.50000	7.50075		7.62345	ns	1,2,4
Name	DIF 166	5.91440		5.99940	6.00000	6.00060		6.11576	ns	1,2,4
al N	DIF 200	4.91450		4.99950	5.00000	5.00050		5.11063	ns	1,2,4
Signal	DIF 266	3.66463		3.74963	3.75000	3.75038		3.85422	ns	1,2,4
S	DIF 333	2.91470		2.99970	3.00000	3.00030		3.10038	ns	1,2,4
	DIF 400	2.41475		2.49975	2.50000	2.50025		2.59782	ns	1,2,4

¹Guaranteed by design and characterization, not 100% tested in production.

² All Long Term Accuracy specifications are guaranteed with the assumption that the input clock complies with CK409/CK410B/CK505 accuracy requirements. The 9DS400/800 itself does not contribute to ppm error.

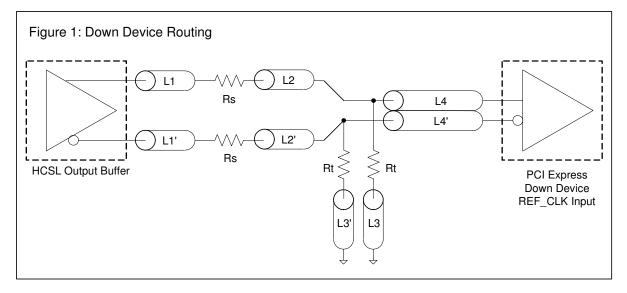
³ Driven by SRC output of main clock, PLL or Bypass mode

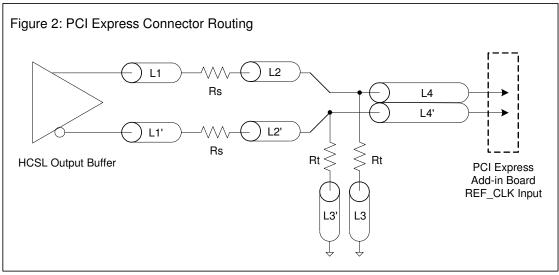
⁴ Driven by CPU output of CK410B/CK505 main clock, **Bypass mode only**

SRC Reference Clock									
Common Recommendations for Differential Routing	Dimension or Value	Unit	Figure						
L1 length, route as non-coupled 50ohm trace	0.5 max	inch	1						
L2 length, route as non-coupled 50ohm trace	0.2 max	inch	1						
L3 length, route as non-coupled 50ohm trace	0.2 max	inch	1						
Rs	33	ohm	1						
Rt	49.9	ohm	1						

Down Device Differential Routing			
L4 length, route as coupled microstrip 100ohm differential trace	2 min to 16 max	inch	1
L4 length, route as coupled stripline 100ohm differential trace	1.8 min to 14.4 max	inch	1

Differential Routing to PCI Express Connector			
L4 length, route as coupled microstrip 100ohm differential trace	0.25 to 14 max	inch	2
L4 length, route as coupled stripline 100ohm differential trace	0.225 min to 12.6 max	inch	2

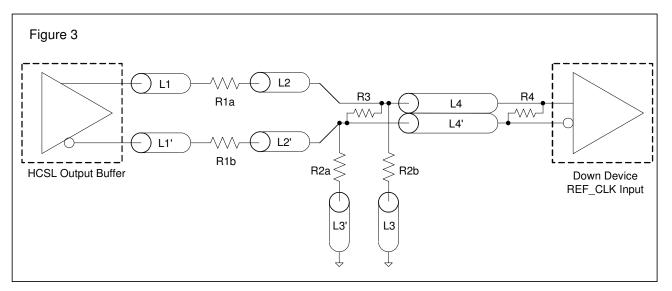




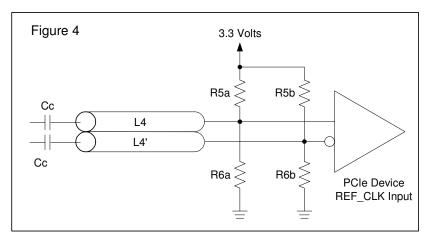
Alternative Termination for LVDS and other Common Differential Signals (figure 3)										
Vdiff Vp-p Vcm R1 R2 R3 R4 Note										
0.22v	1.08	33	150	100	100					
0.28	0.6	33	78.7	137	100					
0.40	0.6	33	78.7	none	100	ICS874003i-02 input compatible				
0.3	1.2	33	174	140	100	Standard LVDS				
	0.22v 0.28 0.40	0.22v 1.08 0.28 0.6 0.40 0.6 0.3 1.2	0.22v 1.08 33 0.28 0.6 33 0.40 0.6 33 0.3 1.2 33	0.22v 1.08 33 150 0.28 0.6 33 78.7 0.40 0.6 33 78.7 0.3 1.2 33 174	0.22v 1.08 33 150 100 0.28 0.6 33 78.7 137 0.40 0.6 33 78.7 none 0.3 1.2 33 174 140	0.22v 1.08 33 150 100 100 0.28 0.6 33 78.7 137 100 0.40 0.6 33 78.7 none 100 0.3 1.2 33 174 140 100				

R1a = R1b = R1

R2a = R2b = R2



Cable Connected AC Coupled Application (figure 4)								
Component	Value	Note						
R5a, R5b	8.2K 5%							
R6a, R6b	1K 5%							
Сс	0.1 μF							
Vcm	0.350 volts							



General SMBus serial interface information for the ICS9DS400

How to Write:

- Controller (host) sends a start bit.
- Controller (host) sends the write address D8 (h)
- ICS clock will *acknowledge*
- Controller (host) sends the begining byte location = N
- ICS clock will *acknowledge*
- Controller (host) sends the data byte count = X
- ICS clock will acknowledge
- Controller (host) starts sending *Byte N through Byte N + X -1*
- ICS clock will acknowledge each byte one at a time
- Controller (host) sends a Stop bit

How to Read:

- Controller (host) will send start bit.
- Controller (host) sends the write address D8 (h)
- ICS clock will acknowledge
- Controller (host) sends the begining byte location = N
- ICS clock will acknowledge
- Controller (host) will send a separate start bit.
- Controller (host) sends the read address D9 (h)
- ICS clock will acknowledge
- ICS clock will send the data byte count = X
- ICS clock sends Byte N + X -1
- ICS clock sends Byte 0 through byte X (if X_(h) was written to byte 8).
- Controller (host) will need to acknowledge each byte
- Controllor (host) will send a not acknowledge bit
- · Controller (host) will send a stop bit

Ind	ex Block W	/rit	e Operation
Cor	ntroller (Host)		ICS (Slave/Receiver)
Т	starT bit		
Slav	e Address D8 _(h)		
WR	WRite		
			ACK
Begi	nning Byte = N		
			ACK
Data	Byte Count = X		
			ACK
Begir	ning Byte N		
			ACK
	\diamond	te	
	\diamond	Byte	♦
	\diamond	×	♦
			◇
Byte	e N + X - 1		
		-	ACK
Р	stoP bit		

Ind	ex Block Rea	ad	Operation		
Con	troller (Host)	IC	S (Slave/Receiver)		
Т	starT bit				
Slave	e Address D8 _(h)				
WR	WRite				
		ACK			
Begii	nning Byte = N				
			ACK		
RT	Repeat starT				
Slave	e Address D9 _(h)				
RD	ReaD				
	-	ACK			
		Data Byte Count = X			
	ACK				
			Beginning Byte N		
	ACK				
		X Byte	\diamond		
	\diamond	б	◇		
	\diamond	×	◇		
	\$				
			Byte N + X - 1		
N	Not acknowledge				
Р	stoP bit				

IDT™/ICS™ Four Output Differential Buffer for PCIe Gen 2 with Spread

SMBus Table: Frequency Select Register, READ/WRITE ADDRESS (D8/D9)

By	te 0 Pin #	Name	Control Function	Туре	0	1	Default
Bit 7	-	PD_Mode	PD# drive mode	RW	driven	Hi-Z	0
Bit 6	-	STOP_Mode	SRC_Stop# drive mode	RW	driven	Hi-Z	0
Bit 5	-		Reserved			0	
Bit 4	1	SPREAD_AMT(1)	Spread % MSB	RW).125% 0.25%	Latch
Bit 3	-	SPREAD_AMT(0)	Spread % LSB	RW	10 = -0.375% 11 = -0.50%		1
Bit 2	28	SPREAD_EN	Turns on spread	RW	SS Off	SS On	Latch
Bit 1	22	BYPASS#	BYPASS#_SSCG	RW	fan-out	SSCG	Latch
Bit 0	-	Byte0 CONTROL	Selects control source of Byte 0	RW	Smbus	Input Pins	1

Notes: Pins 1, 22 and 28 are latched into Byte 0 on the first power up of the device. Bits [4:1] will NOT reflect changes in these pin states after power up, even though the pins are controlling the function of the part. Setting Byte 0 bit 0 to 0 allows the SMBus to write Bits [4:1] and transfers control of the functions from the pins to SMBus. Once Byte 0 bit 0 is set to 0, the pins no longer impact Byte 0, bits [4:1] or the device function.

SMBus Table: Output Control Register

Ву	te 1	Pin #	Name	Control Function	Туре	0	1	Default
Bit 7	-	-	Reserved Reserved RW Reserved		erved	1		
Bit 6	22	,23	DIF_6	Output Enable	RW	Disable	Enable	1
Bit 5	19	,20	DIF_5	Output Enable	RW	Disable	Enable	1
Bit 4		-	Reserved	Reserved	RW	Reserved		1
Bit 3		-	Reserved	Reserved	RW	Rese	Reserved	
Bit 2	9,	10	DIF_2	Output Enable	RW	Disable	Enable	1
Bit 1	6	,7	DIF_1	Output Enable	RW	Disable	Enable	1
Bit 0		-	Reserved	Reserved	RW	Rese	erved	1

NOTE: The SMBus Output Enable Bit must be '1' AND the respective OE pin must be active for the output to run!

SMBus Table: OE Pin Control Register

By	te 2	Pin #	Name	Control Function	Туре	0	1	Default
Bit 7	7 -		- Reserved Reserved		RW	Rese	erved	0
Bit 6	22	,23	DIF_6	DIF_6 Stoppable with OE6	RW	Free-run	Stoppable	0
Bit 5		-	Reserved	Reserved	RW	Reserved		0
Bit 4		-	Reserved	Reserved	RW	Rese	erved	0
Bit 3		-	Reserved	Reserved	RW	Rese	erved	0
Bit 2		-	Reserved	Reserved	RW	Rese	erved	0
Bit 1	6	,7	DIF_1	DIF_1 Stoppable with OE1	RW	Free-run	Stoppable	0
Bit 0		-	Reserved	Reserved	RW	Rese	erved	0

SMBus Table: Reserved Register

Byte 3	Pin #	Name	Control Function	Туре	0	1	Default
Bit 7			Reserved				Х
Bit 6			Reserved				Х
Bit 5			Reserved				Х
Bit 4			Reserved				Х
Bit 3			Reserved				Х
Bit 2			Reserved				Х
Bit 1			Reserved				Х
Bit 0			Reserved				Х

IDT[™]/ICS[™] Four Output Differential Buffer for PCIe Gen 2 with Spread

SMBus Table: Vendor & Revision ID Register

Byte 4	Pin #	Name	Control Function	Туре	0	1	Default
Bit 7	-	RID3		R	-	-	0
Bit 6	-	RID2		R	-	-	0
Bit 5	-	RID1	REVISION ID	R	-	-	0
Bit 4	-	RID0		R	-	-	0
Bit 3	-	VID3		R	-	-	0
Bit 2	-	VID2		R	-	-	0
Bit 1	-	VID1	VENDOR ID	R	-	-	0
Bit 0	-	VID0		R	-	-	1

SMBus Table: DEVICE ID

Byte	e 5	Pin #	Name	Control Function	Туре	0	1	Default
Bit 7	-			Device ID 7 (MSB)	R			Х
Bit 6	-			Device ID 6	R			Х
Bit 5	-			Device ID 5	R			0
Bit 4	-	-		Device ID 4	R	 Device ID is 80 He for 9DS800 and 40 		0
Bit 3	-			Device ID 3	R	Hex for 9DS400		0
Bit 2	-	-		Device ID 2	R	R Hex for 9DS400		0
Bit 1	-			Device ID 1	R			0
Bit 0	-			Device ID 0	R			0

SMBus Table: Byte Count Register

Ву	te 6	Pin #	Name	Control Function	Туре	0	1	Default
Bit 7	-		BC7		RW	-	-	0
Bit 6	-		BC6		RW	-	-	0
Bit 5	-		BC5		RW	-	-	0
Bit 4	-		BC4	Writing to this register configures how	RW	-	-	0
Bit 3	-		BC3	many bytes will be read back.	RW	-	-	0
Bit 2	-		BC2		RW	-	-	1
Bit 1	-		BC1		RW	-	-	1
Bit 0	-		BC0		RW	-	-	1

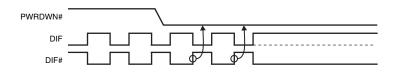
Note: Polarities in timing diagrams are shown $OE_{INV} = 0$. They are similar to $OE_{INV} = 1$.

PD#, Power Down

The PD# pin cleanly shuts off all clocks and places the device into a power saving mode. PD# must be asserted before shutting off the input clock or power to insure an orderly shutdown. PD is asynchronous active-low input for both powering down the device and powering up the device. When PD# is asserted, all clocks will be driven high, or tri-stated (depending on the PD# drive mode and Output control bits) before the PLL is shut down.

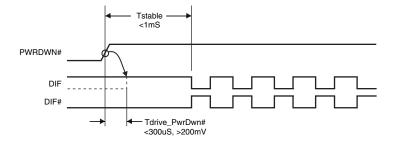
PD# Assertion

When PD# is sampled low by two consecutive rising edges of DIF#, all DIF outputs must be held High, or tri-stated (depending on the PD# drive mode and Output control bits) on the next High-Low transition of the DIF# outputs. When the PD# drive mode bit is set to '0', all clock outputs will be held with DIF driven High with 2 x IREF and DIF# tri-stated. If the PD# drive mode bit is set to '1', both DIF and DIF# are tri-stated.



PD# De-assertion

Power-up latency is less than 1 ms. This is the time from de-assertion of the PD# pin, or VDD reaching 3.3V, or the time from valid SRC_IN clocks until the time that stable clocks are output from the device (PLL Locked). If the PD# drive mode bit is set to '1', all the DIF outputs must driven to a voltage of >200 mV within 300 us of PD# de-assertion.



DIF_STOP#

The DIF_STOP# signal is an active-low asynchronous input that cleanly stops and starts the DIF outputs. A valid clock must be present on DIF_IN for this input to work properly. The DIF_STOP# signal is de-bounced and must remain stable for two consecutive rising edges of DIF# to be recognized as a valid assertion or de-assertion.

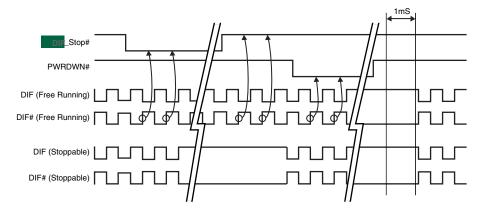
DIF_STOP# - Assertion

Asserting DIF_STOP# causes all DIF outputs to stop after their next transition (if the control register settings allow the output to stop). When the DIF_STOP# drive bit is '0', the final state of all stopped DIF outputs is DIF = High and DIF# = Low. There is no change in output drive current. DIF is driven with $6x_{IREF}$ DIF# is not driven, but pulled low by the termination. When the DIF_STOP# drive bit is '1', the final state of all DIF output pins is Low. Both DIF and DIF# are not driven.

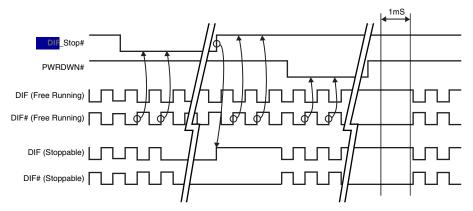
DIF_STOP# - De-assertion (transition from '0' to '1')

All stopped differential outputs resume normal operation in a glitch-free manner. The de-assertion latency to active outputs is 2-6 DIF clock periods, with all DIF outputs resuming simultaneously. If the DIF_STOP# drive control bit is '1' (tri-state), all stopped DIF outputs must be driven High (>200 mV) within 10 ns of de-assertion.

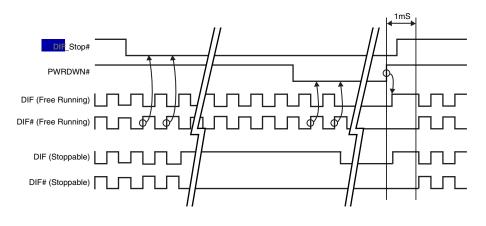
DIF_STOP_1 (DIF_Stop = Driven, PD = Driven)



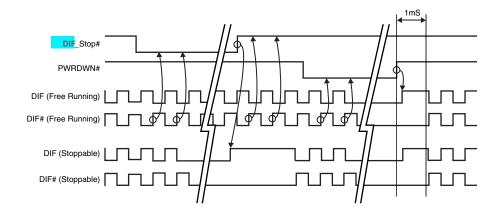
DIF_STOP_2 (DIF_Stop =Tristate, PD = Driven)



DIF_STOP_3 (DIF_Stop = Driven, PD = Tristate)



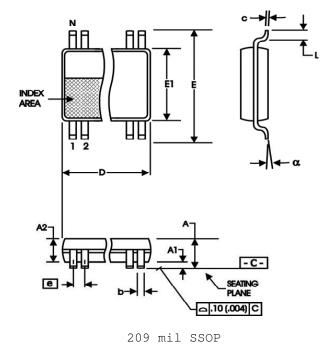
DIF_STOP_4 (DIF_Stop = Tristate, PD = Tristate)



IDT™/ICS™ Four Output Differential Buffer for PCIe Gen 2 with Spread

Advance Information

28-pin SSOP Package Dimensions



209 mil SSOP					
	In Millimeters		In Inches		
SYMBOL	COMMON DIMENSIONS		COMMON DIMENSIONS		
	MIN	MAX	MIN	MAX	
А		2.00		.079	
A1	0.05		.002		
A2	1.65	1.85	.065	.073	
b	0.22	0.38	.009	.015	
С	0.09	0.25	.0035	.010	
D	SEE VARIATIONS		SEE VAF	RIATIONS	
E	7.40	8.20	.291	.323	
E1	5.00	5.60	.197	.220	
е	0.65 BASIC		0.0256	BASIC	
L	0.55	0.95	.022	.037	
Ν	SEE VARIATIONS		SEE VAF	RIATIONS	
α	0°	8°	0°	8°	

VARIATIONS

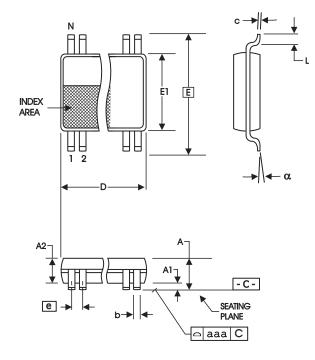
N	D mm.		D (inch)	
IN	MIN	MAX	MIN	MAX
28	9.90	10.50	.390	.413

Reference Doc.: JEDEC Publication 95, MO-150

10-0033

00 1111 5501

28-pin TSSOP Package Dimensions



	(173 mi	il) (25.6 r	nil)		
	In Millimeters		In Inches		
SYMBOL	COMMON DIMENSIONS		COMMON DIMENSIONS		
	MIN	MAX	MIN	MAX	
А		1.20		.047	
A1	0.05	0.15	.002	.006	
A2	0.80	1.05	.032	.041	
b	0.19	0.30	.007	.012	
С	0.09	0.20	.0035	.008	
D	SEE VARIATIONS		SEE VA	RIATIONS	
E	6.40 BASIC		0.252	BASIC	
E1	4.30	4.50	.169	.177	
е	0.65 BASIC		0.0256	BASIC	
L	0.45	0.75	.018	.030	
Ν	SEE VARIATIONS		SEE VA	RIATIONS	
α	0°	8°	0°	8°	
aaa		0.10		.004	

4.40 mm. Body, 0.65 mm. Pitch TSSOP

VARIATIONS

Ν	D mm.		D (inch)	
	MIN	MAX	MIN	MAX
28	9.60	9.80	.378	.386

Reference Doc.: JEDEC Publication 95, MO-153

10-0035

9DS400 Ordering Information

Part / Order Number	Marking	Shipping Packaging	Package	Ambient Operating Temperature
9DS400AGLF	9DS400AGLF	Tubes	28-pin TSSOP	0 to +70° C
9DS400AGLFT	9DS400AGLF	Tape and Reel	28-pin TSSOP	0 to +70° C
9DS400AGILF	9DS400AGILF	Tubes	28-pin TSSOP	-40 to +85° C
9DS400AGILFT	9DS400AGILF	Tape and Reel	28-pin TSSOP	-40 to +85° C
9DS400AFLF	9DS400AFLF	Tubes	28-pin SSOP	0 to +70° C
9DS400AFLFT	9DS400AFLF	Tape and Reel	28-pin SSOP	0 to +70° C
9DS400AFILF	9DS400AFILF	Tubes	28-pin SSOP	-40 to +85° C
9DS400AFILFT	9DS400AFILF	Tape and Reel	28-pin SSOP	-40 to +85° C

Parts that are ordered with a "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

IDT™/ICS™ Four Output Differential Buffer for PCIe Gen 2 with Spread

Revision History

Rev.	Issue Date	Description	Page #
0.1	9/16/2009	Initial release.	
0.2	9/17/2009	Updated IDD specs in Input/Supply/Common Output Parameters table	5

IMPORTANT NOTICE AND DISCLAIMER

RENESAS ELECTRONICS CORPORATION AND ITS SUBSIDIARIES ("RENESAS") PROVIDES TECHNICAL SPECIFICATIONS AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS OR IMPLIED, INCLUDING, WITHOUT LIMITATION, ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for developers skilled in the art designing with Renesas products. You are solely responsible for (1) selecting the appropriate products for your application, (2) designing, validating, and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. Renesas grants you permission to use these resources only for development of an application that uses Renesas products. Other reproduction or use of these resources is strictly prohibited. No license is granted to any other Renesas intellectual property or to any third party intellectual property. Renesas disclaims responsibility for, and you will fully indemnify Renesas and its representatives against, any claims, damages, costs, losses, or liabilities arising out of your use of these resources. Renesas' products are provided only subject to Renesas' Terms and Conditions of Sale or other applicable terms agreed to in writing. No use o any Renesas resources expands or otherwise alters any applicable warranties or warranty disclaimers for these products.

(Disclaimer Rev.1.0 Mar 2020)

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan www.renesas.com

Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners. **Contact Information**

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit: <u>www.renesas.com/contact/</u>